IPC - ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi												2025-05-14			
Contact Name			Title - Contact			I	Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date	Versi	on	Manufacturing Site		V	Veight*	UOM	Unit Type
		LM2596TVADJG 3A BUC		3A BUCK SW RE	A BUCK SW REG 150KHZ		2025-05-14 MY1			1960.42		mg	Each		
	Process Information									1			- I		
3 · · · · · · · · · · · · · · · · · · ·					-STD-020 MS	L Rating			Body Temperature Max Time at Peak				er of Reflow Cyc	cles	
	(Sn) - annealed	C	CU Alloy	N	NA		0		C	30		secono	ds 3		
omments															
r more informatio	on regarding material co	mposition j	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the control of	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.83	mg	A	Lead (Pb)	7439-92-1	7a	78.6885	mg
			Supplier	Tin (Sn)	7440-31-5		4.1415	mg
Lead Frame	1297.64	mg	Supplier	Copper (Cu)	7440-50-8		1297.64	mg
Mold Compound-Black	543.9			Phenolic Resin	proprietary data		32.634	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		54.39	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		40.7925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		413.364	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg